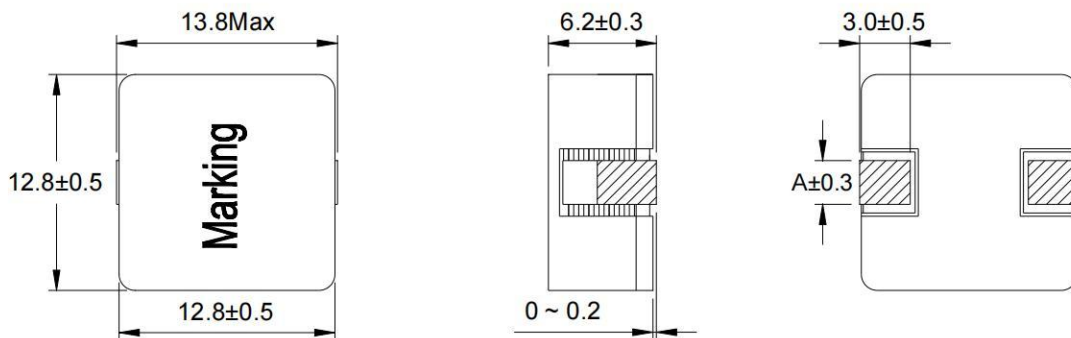


Outline: 产品概要

- Magnetic shielded structure: excellent resistance to electro magnetic interference(EMI)
磁屏蔽结构：抗电磁干扰(EMI)性能强
- Flat wire winding, achieve a low D.C. Resistance.
扁平线绕组，实现极低的直流电阻。
- Low loss, high efficiency, wide application frequency and application scope.
低损耗，高效率，应用频率宽，适用范围广。
- Lightweight design, save space, suitable for high density SMT.
轻薄型设计，节省空间，适合高密度贴装。
- Operating temperature : -55°C ~ +150°C (Including coil's temperature rise)
工作温度：-55°C ~ +150°C (包含线圈发热)

1 Appearance and Dimensions (mm) 外形尺寸 (mm)

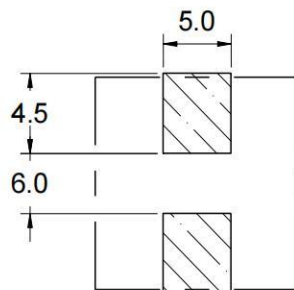


Part No.	R20 – 330	390 – 470
Dimension A	2.5	2.0

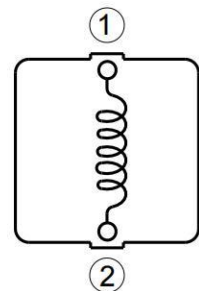
2 Marking 印字标识



3 Reference Land Pattern (mm) 参考基板尺寸 (mm)



4 Schematic 原理图



※ Date code will be changed by manufacture date.
生产日期代码将根据生产日期变动。



5 Electrical Characteristics

电气特性

Part No. 型号	Inductance (μH) 电感值 ※1 ±20%	D.C.R. (mΩ) 直流电阻		Saturation current (A) 饱和电流 ※2 Typical	Temperature rise current (A) 温升电流 ※3 Typical
		Typical	Max		
YZBX 1265-R20M	0.20	0.32	0.37	>110	36.0
YZBX 1265-R47M	0.47	0.65	0.75	90.0	32.0
YZBX 1265-R85M	0.85	0.90	1.05	63.0	26.0
YZBX 1265-1R3M	1.30	1.69	1.95	50.0	25.0
YZBX 1265-2R0M	2.00	2.25	2.60	41.0	23.0
YZBX 1265-2R7M	2.70	3.25	3.75	35.0	20.0
YZBX 1265-3R6M	3.60	4.20	4.85	30.0	17.0
YZBX 1265-4R7M	4.70	5.42	6.25	27.0	14.0
YZBX 1265-5R8M	5.80	6.93	7.97	24.0	12.0
YZBX 1265-7R3M	7.30	5.68	6.50	18.5	13.0
YZBX 1265-9R2M	9.20	7.24	8.35	16.3	12.0
YZBX 1265-110M	11.0	8.87	10.2	15.0	11.0
YZBX 1265-130M	13.0	10.2	11.7	13.5	10.0
YZBX 1265-150M	15.0	12.3	14.1	12.5	9.00
YZBX 1265-180M	18.0	15.2	17.5	11.2	8.50
YZBX 1265-220M	22.0	18.6	21.5	10.7	8.00
YZBX 1265-270M	27.0	23.9	27.5	9.50	6.50
YZBX 1265-330M	33.0	26.3	30.3	8.80	5.50
YZBX 1265-390M	39.0	40.3	46.5	8.00	4.50
YZBX 1265-470M	47.0	54.5	62.7	7.20	4.00

- All data is tested based on 25°C ambient temperature.
所有数据基于环境温度 25°C条件下测试。

※1 Inductance measure condition at 100kHz, 0.5V.

电感测试条件为 100kHz, 0.5V。

※2 Saturation current : the actual value of DC current when the inductance decrease 30% of its initial value.

饱和电流 : 电感值下降其初始值的 30%时所加载的实际直流电流值。

※3 Temperature rise current : the actual value of DC current when the temperature rise is ΔT50°C(Ta=25°C).

温升电流 : 使产品温度上升到 ΔT50°C时所加载的实际直流电流值(Ta=25°C)。

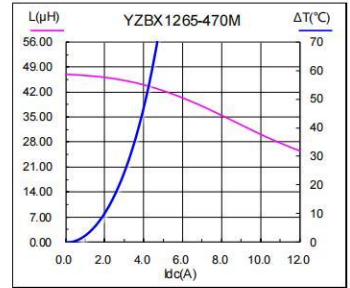
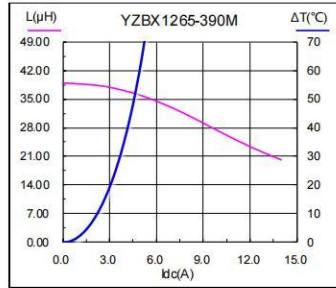
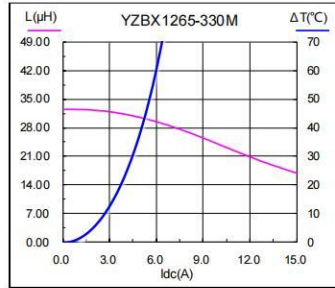
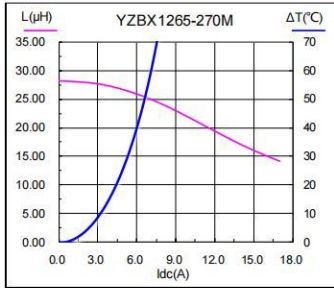
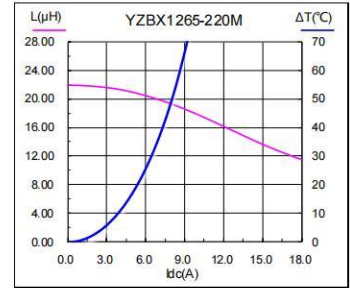
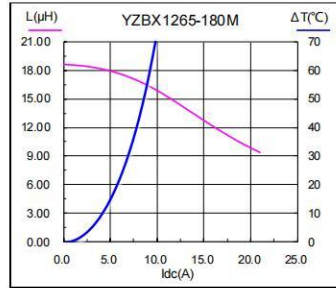
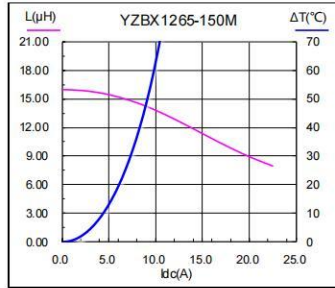
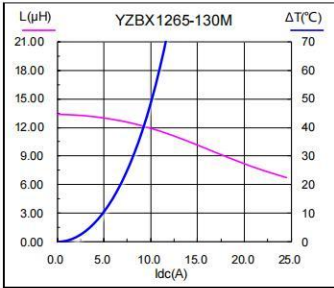
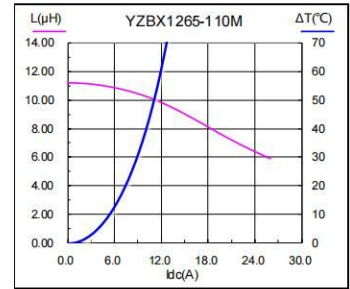
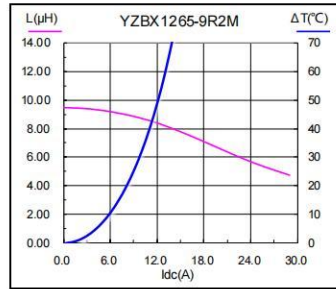
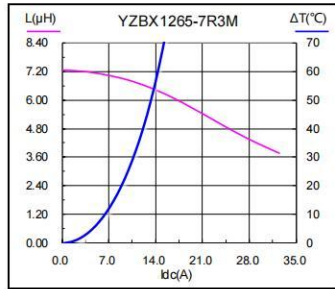
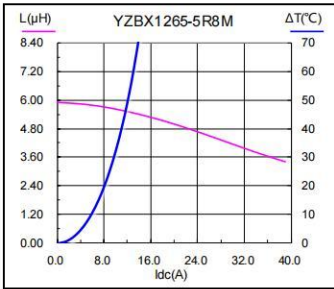
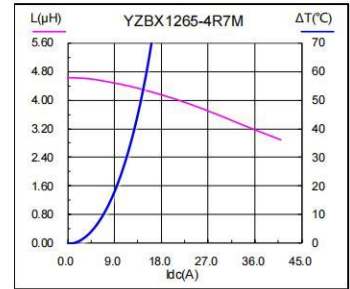
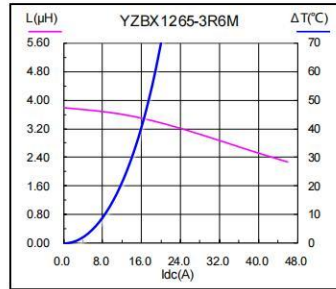
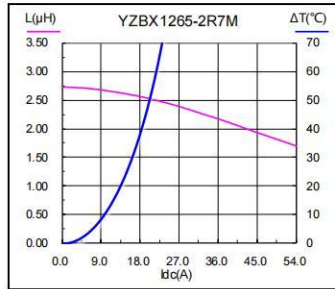
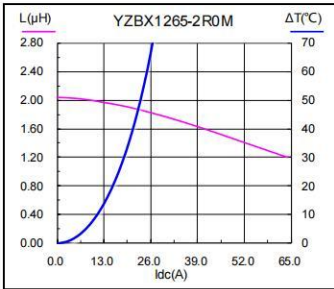
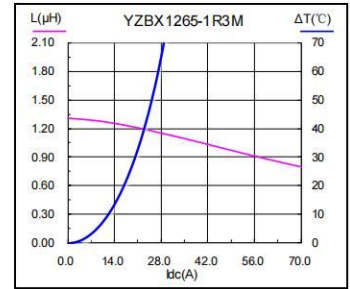
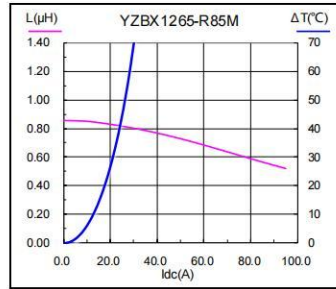
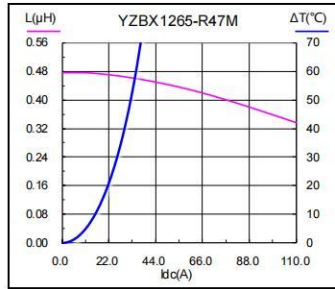
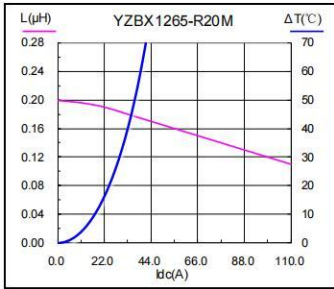
※ Special remind : Circuit design, component placement, PCB size and thickness, cooling system and etc. all will affect the product temperature. Please verify the product temperature in the final application.

特别提醒 : 线路设计, 组件布局, 印刷电路板(PCB)尺寸及厚度, 散热系统等均会影响产品温度。

请务必在最终应用时, 验证产品发热状况。



6 Saturation Current vs Temperature Rise Current Curve 饱和电流 vs 温升电流曲线



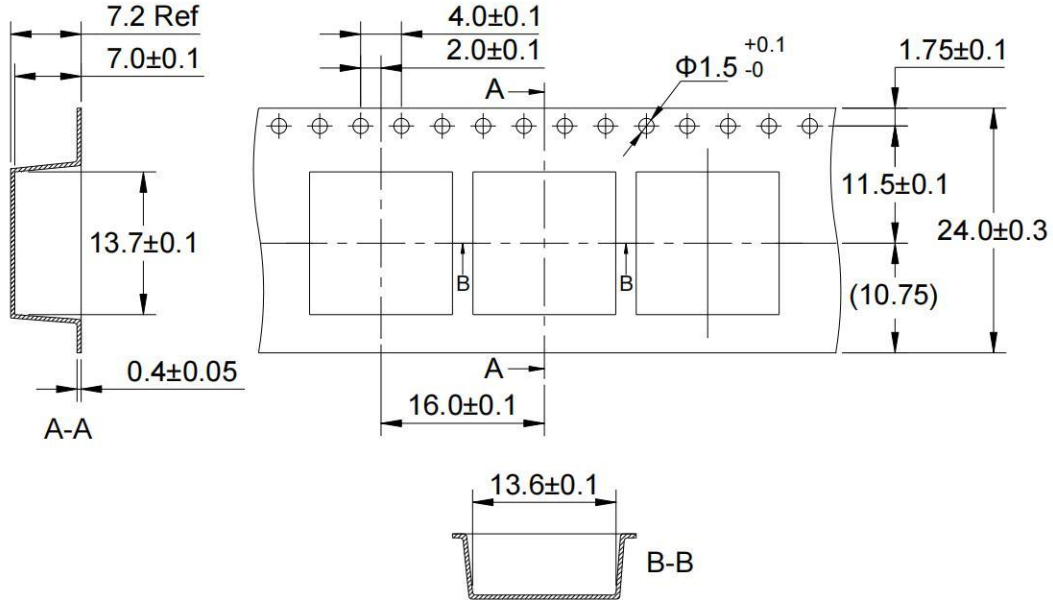


7 Packing Specification

包装规格

7.1 Carrier Tape Dimensions (mm)

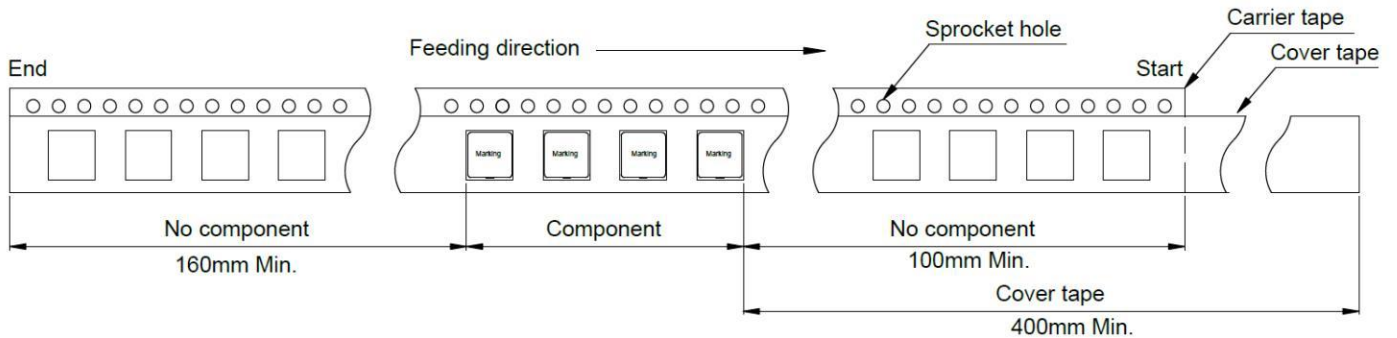
载带尺寸



※ Packing is referred to the international standard IEC 60286-3.
包装参照国际标准 IEC 60286-3。

7.2 Tape Direction

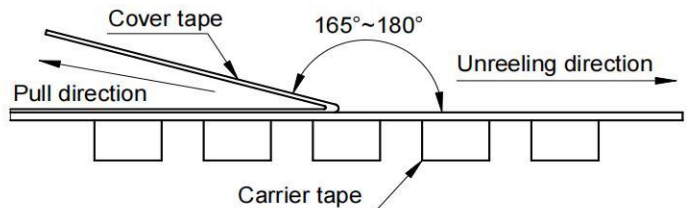
捆包方向



7.3 Cover Tape Peel Off Condition

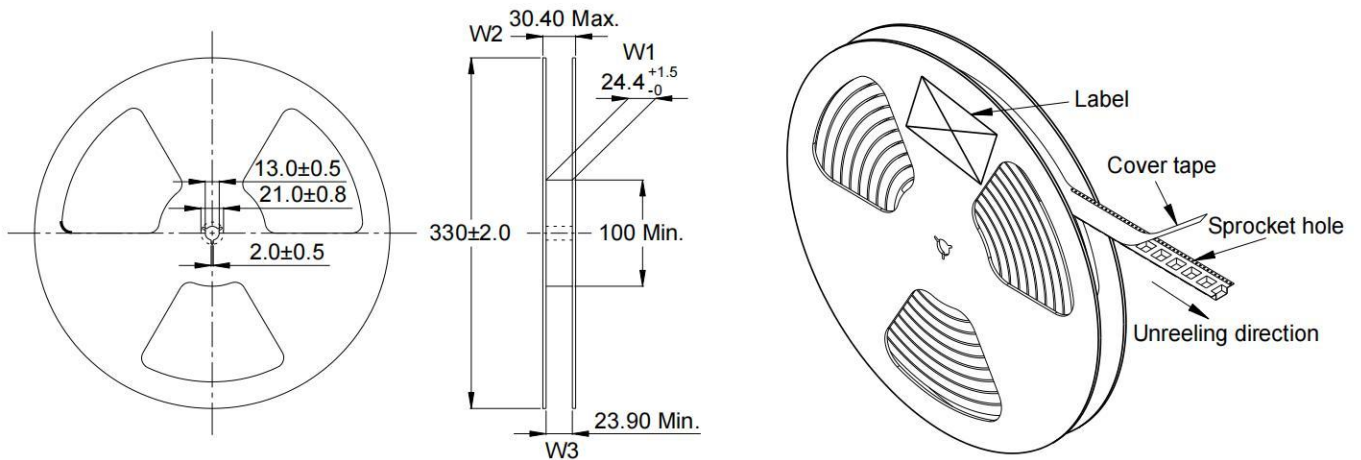
盖带剥离条件

- Cover tape peel force shall be 0.1 to 1.3N.
盖带剥离力度为 0.1 ~ 1.3N。
- Reference peel speed 300±10mm/min.
参考剥离速度 300±10mm/分钟。





7.4 Reel Dimensions (mm)
卷盘尺寸



7.5 Carton Dimensions and Packing Quantity
包装箱尺寸和包装数量

■ Inner Carton : 340×340×95mm
内包装盒

■ Out Carton : 360×360×370mm
外包装箱

Product Series 产品系列	Quantity / Reel 数量 / 卷	Inner Carton Quantity 内盒 包装数量	Out Carton Quantity 外箱 包装总数量
YZBX1265	400pcs	800pcs = (2×400)	2400pcs = (3×800)

7.6 Label Making
标签标识

The following items will be marked on the reel of product label and shipping label.
以下项目将明确标识于产品卷盘标签以及运输标签上。

Production Label 产品标签
■ Packing No. 包装流水号
■ Quantity 数量
■ Shipment Date 出货日期
■ Part No. 产品型号
■ Customer Part No. 客户型号
■ Customer Po No. 客户订单号

Shipping Label 运输标签
■ Packing No. 包装流水号
■ Quantity 数量
■ Shipment Date 出货日期
■ Part No. 产品型号
■ Customer Part No. 客户型号
■ Customer Po No. 客户订单号

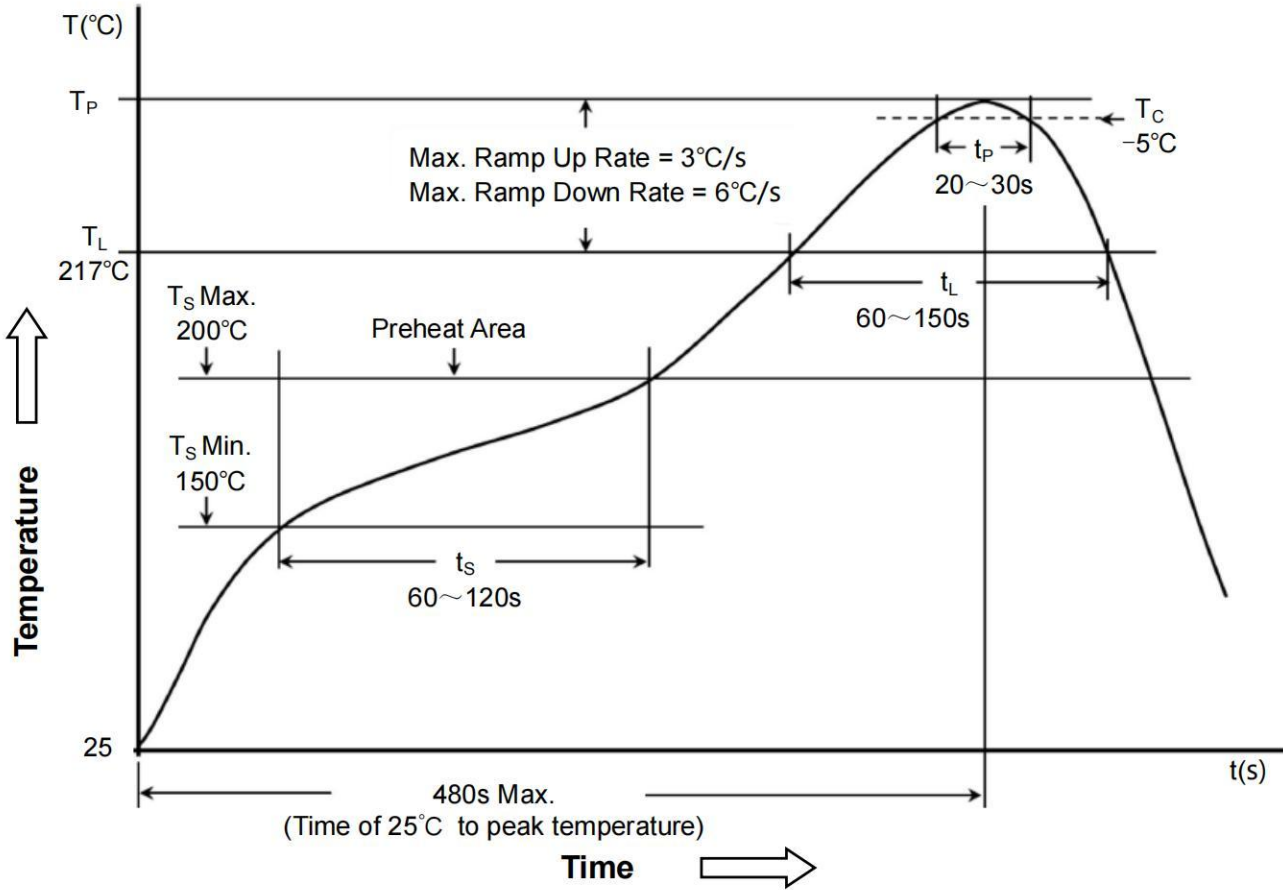


8 Soldering specification

焊接规格

8.1 Reflow profile for SMT components

SMT 回流焊温度曲线



8.2 Classification of peak package body temperature (T_P)

封装体峰值温度(T_P)分类

	Package Thickness 封装厚度	Package Volume 封装体积		
		<350 mm ³	350 ~ 2000 mm ³	>2000 mm ³
PB-Free Assembly 无铅装配	<1.6mm	260°C	260°C	260°C
	1.6 ~ 2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.

回流焊参照标准 IPC/JEDEC J-STD-020D.